

TAIEX: 6552

2020/08/26

- * JMC's statements of its current expectations are forward looking statements subject to significant risks and uncertainties and actual results may differ materially from those contained in the forward-looking statements.
- * Except as required by law, we undertake no obligation to update any forward-looking statement, whether as a result of new information, future events, or otherwise.

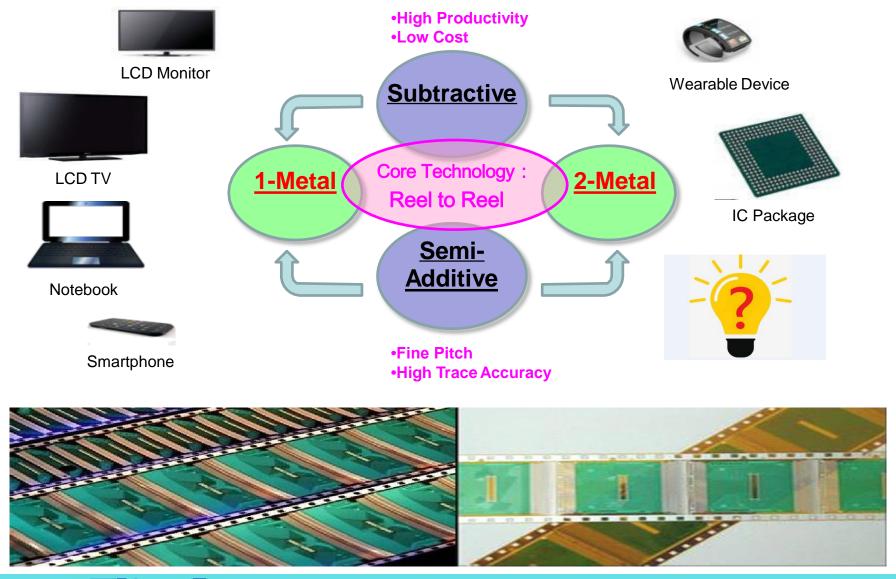


1. Company Introduction - Company Snapshot

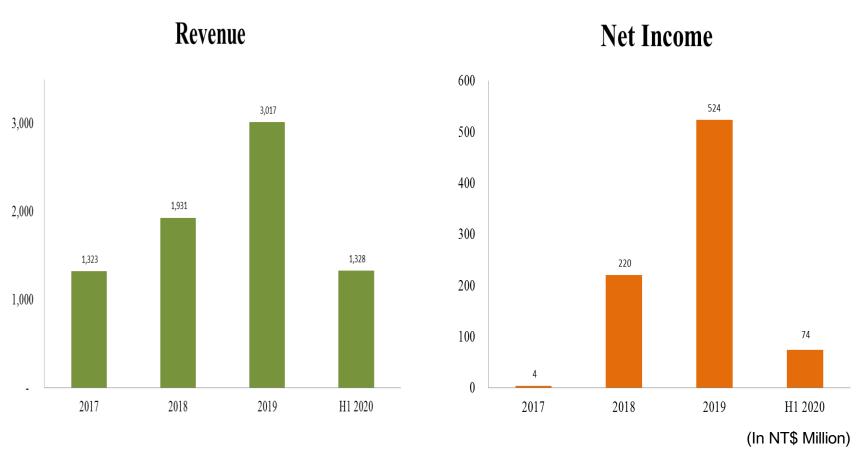
- Established : October 6 ,1973
- Chairman : Canon Huang
- General Manager : Jane Lee
- Capital Stock : 1,000 million
- Major Shareholders: CWE 42%、ChipMos 10%
- Number of employees as of Jun. 30,2020: 789
- Major Product : COF(Reel to Reel Chip on Film)
- Headquarter : Kaohsiung, Taiwan



1. Company Introduction - Product Application



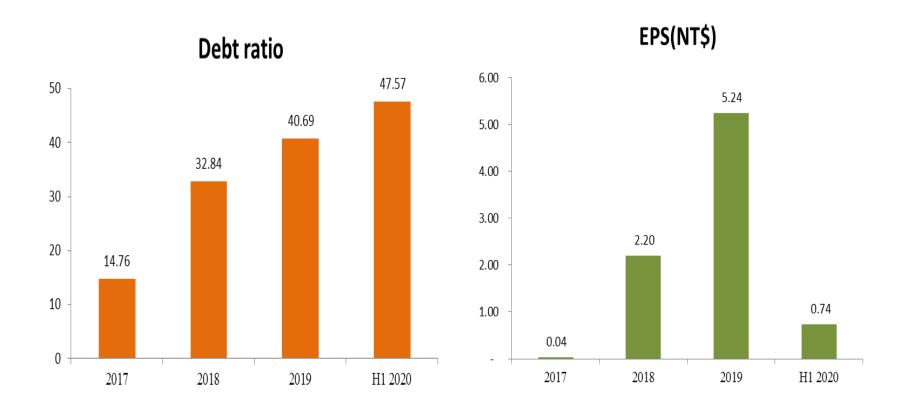
2. Financial Results - Results Highlights



Year	2017	2018	2019	H1 2020
Revenue	1,323	1,931	3,017	1,328
Net Income	4	220	524	74



2. Financial Results - Results Highlights



Year	2017	2018	2019	H1 2020
Debt Ratio(%)	14.76	32.84	40.69	47.57
EPS(NT\$)	0.04	2.20	5.24	0.74



2. Financial Results - Results Highlights



Year	2017	2018	2019	H1 2020
A/R Turnover Ratio	6.60	6.60	7.26	5.94
Inventory Turnover ratio	6.51	7.83	8.47	8.68



3. Market & Business Overview - Large Panel

✓ Currently – COVID-19 affects consumption and leads to weaker demand

- * COVID-19 affects consumer willingness, and leads to weaker demand.
- * Fab orders surge due to 5G and automotive demand ,and crowds out the capacity supply of low-margin products, such as LCD driver IC.
- * The overall inventory of LCD driver IC is currently falling. However, because of the FAB capacity limitation and LCD driver inventory consumption, when the demand of follow-up market recovers, it is expected that there will be a short-term emergency pull situation, and yet somehow the long-term supply and demand will be more stable.

✓ <u>Future trend – New design and application</u>; <u>Trend unchanged</u>; <u>Demand time deferred</u>

- * TV Panel 4K to 8K, Dual Cell.
- * Monitor/NB/Tablet Panel COG moves to COF due to full-screen/narrow edge design.
- * Automotive Panel comes to COF.



3.Market & Business Overview – Small Panel

✓ Currently – Market is in chaos.

- * COVID-19 affects consumer willingness, coupled with the U.S.-China trade war on Huawei's IC supply restrictions, and the China-Indian border conflict has an impact on the sales of MI phone, all leads to weaker demand.
- * Fab orders surge due to 5G and automotive demand ,and crowds out the capacity supply of low-margin products, such as LCD driver IC.
- * In the short term, the smartphone LCD driver IC market is full of obscure, and the market is still changing rapidly.

✓ <u>Future trend – New design and application</u>; <u>Trend unchanged</u>; <u>Demand time</u> <u>deferred</u>

- * High-end Smartphone with Flexable OLED: COP / 1-Metal COF.
- * Mid-range Smartphone with Rigid OLED/LTPS: FHD TDDI/FTDDI uses 1-Metal COF / partial COG.
- * Low-end Smartphone with a-Si/LTPS: HD uses COG / FHD TDDI uses 1-Metal COF.
- * Wearable Device: The design turns to <u>1-Metal COF</u> instead of COG due to the narrow border panel. The market is still growing up.



3.Market & Business Overview - Technology & Product Development

✓ A full service of flexible IC substrate provider

Process Technology	Competitive advantages	Technology/ Application	Targeted Market/ Development
1-Metal Subtractive (Etching)	Fast production and high efficiency.Independent technical ability and stable production yield.	*Copper thickness #~8um *Pitch >=20um Pitch *Pin count =<1440 Channel/48mm	@ LCD TV @ OLED TV @ Dual Cell LCD
1-Metal Semi- Additive (Plating)	 High precision size controlled COF products, and can improve the assembly of the panel module rate; help customers to lower total cost. High production yield and good quality stability; absolute competitive advantage in production costs. 	*Copper thickness #~12um *Pitch >=18/16/14um Pitch *Pin count =<1900 Channel/48mm =<3000 Channel/70mm	 @ High-end smartphone @ wearable device @ FoD @ FTDDI
 New process technology development capabilities. Equipment design capability. Good cost control. 		*Thin Film IC Substrate *LED IC Substrate *Pin count =<2500 Channel/48mm =<4000 Channel/70mm	@ NAND Flash@ Mini LED@ Micro LED



4.Industry Outlook - Driver IC Supply Chain

IC Design House provides total solution.



Five COF suppliers have mass production capacity currently, and JMC is just one of the two vendors in Taiwan.

Process Technology		logy	1-Metal Subtractive(Etching)	1-Metal Semi-Additive(Plating)	2-Metal
	Channel/48mm		=<1400 /48mm	1400~1900 /48mm	1900~2500 /48mm
Application	Channel/70mm		=<2000 /70mm	2000~3000 /70mm	3000~4000 /70mm
Capacity		S社	90~100KK	?KK(2-Metal→1-Metal)	7-10KK
	Korea	L社	120~130KK	?KK(2-Metal→1-Metal)	5-7KK
	Japan	F社	20KK	Х	2KK
	C社 Taiwan JMC	70~90KK	Х	Х	
		JMC	30KK+10KK (Restarting)	40KK	5KK(Installing)
	China	ESWIN Aplus	?	? ?	?



Q&A

